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FACSIMILE TRANSMITTAL COVER SHEET

Date: January 27, 2003

No. of Pages (including this page): 10 *2827*

To: Examiner Luan C. Thai
U.S. Patent & Trademark Office
Washington, DC 20231

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Message:

Re: Extension of Time and Amendment
First Named Inventor: Hogerton, Peter B.
Application No.: 09/690,600
Case No.: 53434US009

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32692
PATENT TRADEMARK OFFICEPatent
Case No. 53434US009

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

First Named Inventor: HOGERTON, PETER B.

Application No.: 09/690,600

Group Art Unit: 2827

Filed: October 17, 2000

Examiner: Luan C. Thal

Title: SOLVENT ASSISTED BURNISHING OF PRE-UNDERFILLED SOLDER-BUMPED WAFERS FOR FLIPCHIP BONDING

AMENDMENT UNDER 37 C.F.R. § 1.111Commissioner for Patents
Washington, DC 20231

CERTIFICATE OF TRANSMISSION	
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I hereby certify that this correspondence is being facsimile transmitted to the U.S. Patent and Trademark Office on:	
<u>27 Jan 2003</u> Date	<u>Dean M. Harts</u> Dean M. Harts

Dear Sir:

The following amendment and remarks are submitted in response to the Office Action
dated September 25, 2002.

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In the Specification

On pages 11-12, please replace the following paragraph starting on page 11 line 26 and ending on page 12 line 9:

To ensure a better electrical connection with a substrate, it is preferred to at least partially remove the adhesive protuberances 28 that cover the bumps 24. As shown in Fig. 1B, an abrasion process is employed to remove the adhesive material located on top of the bumps 24 exposing the conductive bumps 24 for better electrical connection with a packaging substrate. In the abrasion process, an abrasive material 32 such as sandpaper, micro abrasive, abrasive pads available from 3M Company, St. Paul, MN under the trade designation Scotch Brite, a cloth, a scraping blade or a coating knife is brought in contact with the adhesive protuberances 28 that cover the bumps 24 such that the bumps 24 are exposed for electrical conduction. Because the